

Agenda

Date August 6, 2020
Time 16:30 – 17:45 h (CEST)
Format Web-Seminar

OE-A Web-Seminar | Printed Electronics Insights Special Topic: Smart Packaging

As a part of **OE-A's web-seminar series 'Printed Electronics Insights'** this web-seminar covers the special topic of **smart packaging**. As packaging becomes more than just an object to contain and display a product, the packaging industry is transforming more and more. Due to its thin, lightweight and flexible features, organic and printed electronics is a true enabler for a multitude of new innovative products in the packaging industry. Printed batteries to power sensors for improved product logistics or cool-chain monitoring, RFID and NFC functionality to facilitate immediate cross-media interaction with the customer at the point of purchase, improved waste management, or even smart blister packs for medical products - these are only a few applications that have already been enabled by printed electronics. Renown industry experts will talk about the latest developments and applications of printed electronics that will drive forward the transformation of the packaging industry.

16.30 Welcome and Introduction

Klaus Hecker, Managing Director, OE-A

16.35 Introduction OE-A Roadmap: Smart Packaging

Jan Krausmann, Project Manager, OE-A

16.40 The next thin thing

Carolina Gioscio, Marketing Manager, Evonik Creavis

16.55 Interact! - How to enable manifold potentials for intelligent packaging with Printed Electronics

Wolfgang Mildner, Founder and Owner, MSWtech

17.10 Compostable RFID antennas by leveraging nano-copper inks

Ofer Shochet, Founder and CEO, Copprint

17.25 Q&A Session

Klaus Hecker, Managing Director, OE-A

17.45 End of Web-Seminar

Contact: Jan Krausmann
Phone: +49 69 6603-1856
E-Mail: jan.krausmann@oe-a.org

Daria Firlus
+49 69 6603-1737
daria.firlus@oe-a.org

A working group within